

# 600 V, 1.0 A Ultrafast Rectifier

# MURHS160T3, NRVUHS160V, SURHS8160

#### **Features and Benefits**

- Ultrafast 35 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 V
- NRVUHS and SURHS8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

# **Applications**

- Power Supplies
- Inverters
- Free Wheeling Diodes

## **Mechanical Characteristics**

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Cathode Polarity Band

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	600	>
Average Rectified Forward Current (Rated V <sub>R</sub> , T <sub>L</sub> = 145°C)	I <sub>F(AV)</sub>	1.0	Α
Nonrepetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	15	Α
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175	°C
ESD Ratings: Charged Device Model Human Body Model = 3B		> 1000 > 8000	٧

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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# 1.0 AMPERES 600 VOLTS



SMB CASE 403A PLASTIC



### **MARKING DIAGRAM**



UH16 = Specific Device Code AL = Assembly Location

Y = Year WW = Work Week • = Pb-Free Package

(Note: Microdot may be in either location)

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MURHS160T3G NRVUHS160VT3G NRVUHS160VT3G-GA01 SURHS8160T3G SURHS8160T3G-GA01	SMB (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **MURHS160T3, NRVUHS160V, SURHS8160**

# THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Lead (Note 1)	$R_{ hetaJL}$	24	°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	80	°C/W

<sup>1.</sup> Mounted with minimum recommended pad size, PC Board FR4.

# **ELECTRICAL CHARACTERISTICS**

Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 3) (I <sub>F</sub> = 1.0 A, T <sub>C</sub> = 25 $^{\circ}$ C) (I <sub>F</sub> = 1.0 A, T <sub>C</sub> = 125 $^{\circ}$ C)	V <sub>F</sub>	1.5 1.2	2.4 1.7	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, T <sub>C</sub> = 25°C) (Rated dc Voltage, T <sub>C</sub> = 125°C)	I <sub>R</sub>	0.18 5.0	20 200	μΑ
Maximum Reverse Recovery Time (I <sub>F</sub> = 1.0 A, di/dt = 50 A/ $\mu$ s) (I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>REC</sub> = 0.25 A)	t <sub>rr</sub>	25 16	35 30	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2.0%.

<sup>2. 1</sup> inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

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# **TYPICAL CHARACTERISTICS**

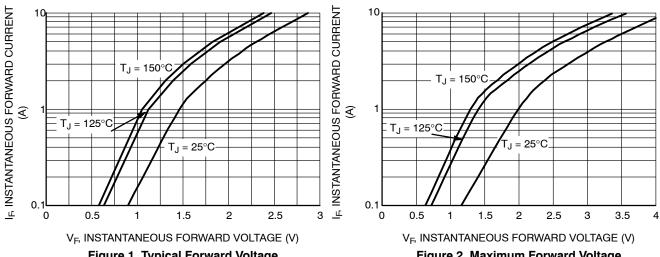
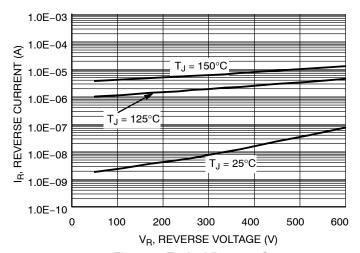


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

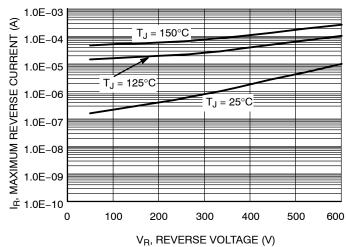


Figure 4. Maximum Reverse Current

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# **TYPICAL CHARACTERISTICS**

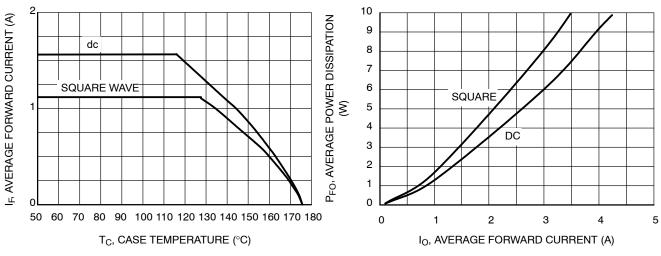


Figure 5. Current Derating

Figure 7. Forward Power Dissipation

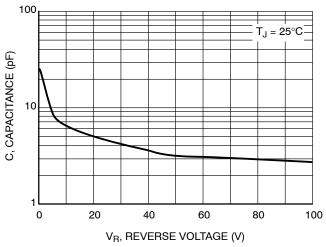


Figure 6. Capacitance

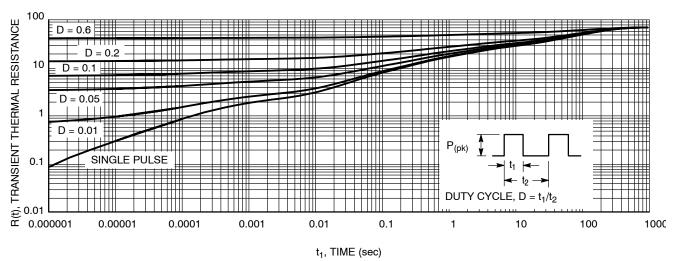


Figure 8. Thermal Response Junction-to-Ambient





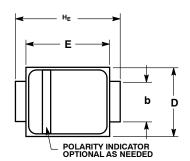


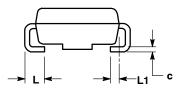
**SMB** CASE 403A-03 **ISSUE J** 

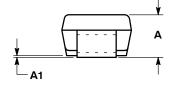
**DATE 19 JUL 2012** 

**Polarity Band** 

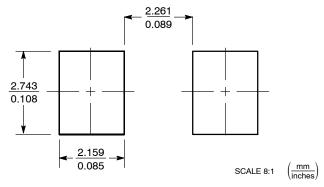
SCALE 1:1 Non-Polarity Band







#### **SOLDERING FOOTPRINT\***



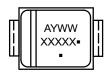
\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCL.
- CONTROLLING DIMENSION: INCH.
  DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.95	2.30	2.47	0.077	0.091	0.097	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.96	2.03	2.20	0.077	0.080	0.087	
С	0.15	0.23	0.31	0.006	0.009	0.012	
D	3.30	3.56	3.95	0.130	0.140	0.156	
E	4.06	4.32	4.60	0.160	0.170	0.181	
HE	5.21	5.44	5.60	0.205	0.214	0.220	
L	0.76	1.02	1.60	0.030	0.040	0.063	
L1		0.51 REF			0.020 REF		

# **GENERIC MARKING DIAGRAM\***





**Polarity Band** 

Non-Polarity Band

XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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